

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>DA SOON LEE</td> <td>10/28/2013</td> </tr> <tr> <td>HYUNG SUK CHOI</td> <td>10/28/2013</td> </tr> <tr> <td>JEONG GYU PARK</td> <td>10/28/2013</td> </tr> <tr> <td>GIL HO LEE</td> <td>10/28/2013</td> </tr> <tr> <td>HYUN TAE JUNG</td> <td>10/28/2013</td> </tr> <tr> <td>MENG AN JUNG</td> <td>10/28/2013</td> </tr> <tr> <td>WOO SIG MIN</td> <td>10/28/2013</td> </tr> <tr> <td>PIL SEUNG KANG</td> <td>10/28/2013</td> </tr> </tbody> </table>		Name	Execution Date	DA SOON LEE	10/28/2013	HYUNG SUK CHOI	10/28/2013	JEONG GYU PARK	10/28/2013	GIL HO LEE	10/28/2013	HYUN TAE JUNG	10/28/2013	MENG AN JUNG	10/28/2013	WOO SIG MIN	10/28/2013	PIL SEUNG KANG	10/28/2013
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RECEIVING PARTY DATA																			
Name:	MAGNACHIP SEMICONDUCTOR, LTD.																		
Street Address:	1 HYANGJEONG-DONG, HEUNGDEOK-GU, CHEONGJU-SI, CHUNGCHONGBUK-DO, 361-728																		
City:	CHEONGJU-SI																		
State/Country:	KOREA, REPUBLIC OF																		
PROPERTY NUMBERS Total: 1																			
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14067335</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14067335														
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Application Number:	14067335																		
CORRESPONDENCE DATA																			
Fax Number:	(202)315-3758																		
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Email:	pto@nsiplaw.com																		
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>																			
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PATENT

NAME OF SUBMITTER:	S. LAURA CHUNG
Signature:	/S. Laura Chung/
Date:	10/30/2013
Total Attachments: 3 source=NewApp_0231030089_CDAwAppNumber#page1.tif source=NewApp_0231030089_CDAwAppNumber#page2.tif source=NewApp_0231030089_CDAwAppNumber#page3.tif	

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)**DECLARATION**

As a below-named inventor, I hereby declare that this declaration is directed to the application attached hereto, or to United States Application Number or PCT International Application Number

_____ filed on _____ (if applicable), entitled:

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

ASSIGNMENT

For valuable consideration, I, as a below-named assignor, hereby assign to:

MagnaChip Semiconductor, Ltd.
1 Hyangjeong-dong, Heungdeok-gu,
Cheongju-si, Chungcheongbuk-do, 361-728
Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number 14/067,335 filed on October 30, 2013.

I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

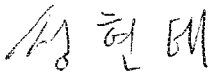
Inventor's Legal Name	LEE, Da Soon		
Inventor's Signature	<i>Da Soon Lee</i>	Date	2013. 10. 28.
Residence (City, Country)	Cheongju-si, Republic of Korea		
Mailing Address	c/o MagnaChip Semiconductor, Ltd., 1 Hyangjeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-728, Republic of Korea		

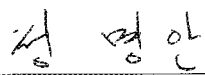
Inventor's Legal Name	CHOI, Hyung Suk		
Inventor's Signature	<i>최흥석</i>	Date	2013. 10. 28
Residence (City, Country)	Cheongju-si, Republic of Korea		
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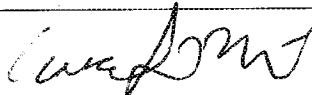
Inventor's Legal Name	PARK, Jeong Gyu		
Inventor's Signature	<i>박정규</i>	Date	2013. 10. 28
Residence (City, Country)	Cheongju-si, Republic of Korea		
Mailing Address	c/o MagnaChip Semiconductor, Ltd., 1 Hyangjeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-728, Republic of Korea		

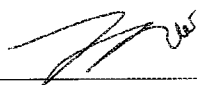
Inventor's Legal Name	LEE, Gil Ho		
Inventor's Signature	<i>이길호</i>	Date	2013. 10. 28
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Inventor's Legal Name	MIN, Woo Sig		
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